imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

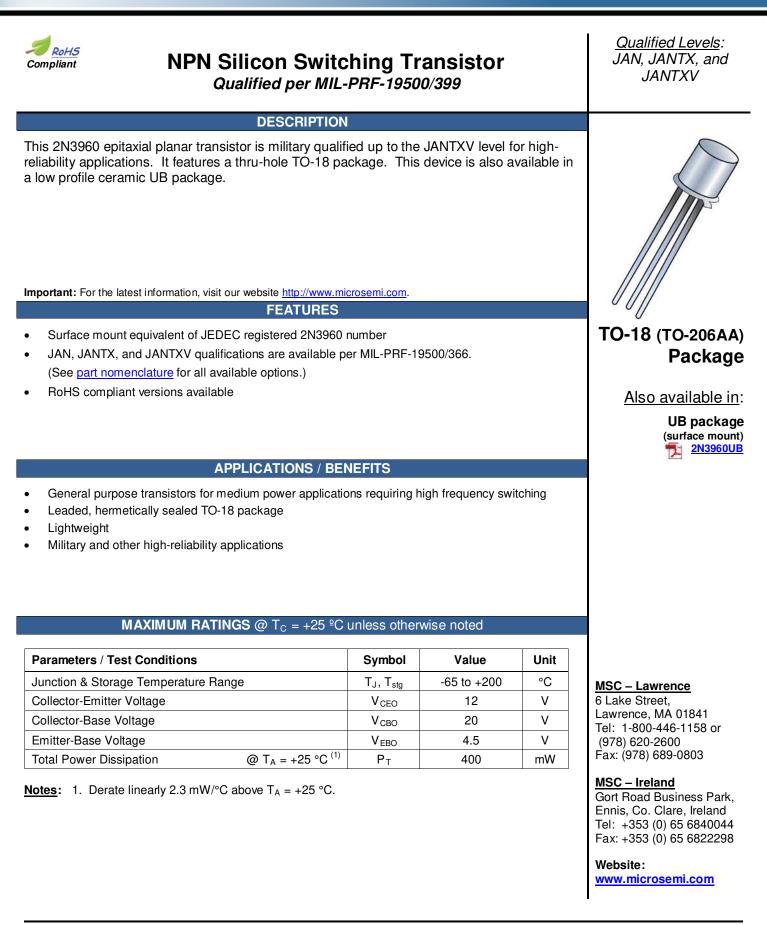


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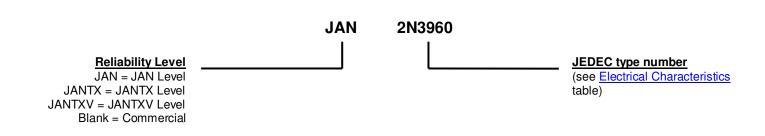




MECHANICAL and PACKAGING

- CASE: Hermetically sealed, nickel plated kovar base, nickel cap
- TERMINALS: Kovar with Gold plate over nickel for JANS, plus solder dip for JAN, JANTX, and JANTXV
- MARKING: Part number, date code, manufacturer's ID
- WEIGHT: Approximately 0.3 grams
- See <u>Package Dimensions</u> on last page.

PART NOMENCLATURE



SYMBOLS & DEFINITIONS					
Symbol	Definition				
IB	Base current: The value of the dc current into the base terminal.				
Ι _C	Collector current: The value of the dc current into the collector terminal.				
V _{CB}	Collector-base voltage: The dc voltage between the collector and the base.				
V _{CBO}	Collector-base voltage, base open: The voltage between the collector and base terminals when the emitter terminal is open-circuited.				
V _{CE}	Collector-emitter voltage: The dc voltage between the collector and the emitter.				
V _{CEO}	Collector-emitter voltage, base open: The voltage between the collector and the emitter terminals when the base terminal is open-circuited.				
V _{CC}	Collector-supply voltage: The supply voltage applied to a circuit connected to the collector.				
V _{EB}	Emitter-base voltage: The dc voltage between the emitter and the base				
V _{EBO}	Emitter-base voltage, collector open: The voltage between the emitter and base terminals with the collector terminal open-circuited.				



ELECTRICAL CHARACTERISTICS @ T_A = +25 °C, unless otherwise noted

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
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OFF CHARACTERISTICS

Collector-Emitter Breakdown Voltage $I_{c} = 10 \ \mu$ A, pulsed	V _{(BR)CEO}	12		V
Collector-Base Cutoff Current $V_{CB} = 20 V$	I _{CBO}		10	μA
Emitter-Base Cutoff Current $V_{EB} = 4.5 V$	I _{EBO}		10	μA
	I _{CEX1} I _{CEX2}		1 5	μA nA

ON CHARACTERISTICS (1)

Forward-Current Transfer Ratio $I_{C} = 1.0 \text{ mA}, V_{CE} = 1 \text{ V}$ $I_{C} = 10 \text{ mA}, V_{CE} = 1 \text{ V}$ $I_{C} = 30 \text{ mA}, V_{CE} = 1 \text{ V}$	h _{FE}	40 60 30	300	
Collector-Emitter Saturation Voltage $I_{C} = 1.0 \text{ mA}, I_{B} = 0.1 \text{ mA}$ $I_{C} = 30 \text{ mA}, I_{B} = 3.0 \text{ mA}$	V _{CE(sat)}		0.2 0.3	V
Base-Emitter Saturation Voltage $I_{C} = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_{C} = 30 \text{ mA}, V_{CE} = 1.0 \text{ V}$	V _{BE}		0.8 1.0	V

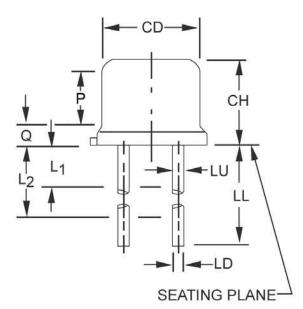
DYNAMIC CHARACTERISTICS

Forward Current Transfer Ratio, Magnitude $I_C = 5.0 \text{ mA}, V_{CE} = 4 \text{ V}, f = 100 \text{ MHz}$ $I_C = 10 \text{ mA}, V_{CE} = 4 \text{ V}, f = 100 \text{ MHz}$ $I_C = 30 \text{ mA}, V_{CE} = 4 \text{ V}, f = 100 \text{ MHz}$	h _{fe}	13 14 12		
Output Capacitance V _{CB} = 4 V, I _E = 0, 100 kHz \leq f \leq 1 MHz	C _{obo}		2.5	pF
Input Capacitance V_{EB} = 0.5 V, I _C = 0, 100 kHz \leq f \leq 1.0 MHz	C _{ibo}		2.5	pF

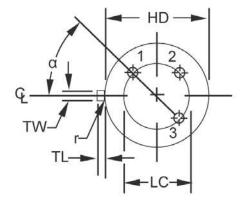
(1) Pulse Test: pulse width = 300 $\mu s,$ duty cycle $\leq 2.0\%$



PACKAGE DIMENSIONS



	Dimensions				
Symbol	Inch		Millimeters		Note
	Min	Max	Min	Max	
CD	0.178	0.195	4.52	4.95	
СН	0.170	0.210	4.32	5.33	
HD	0.209	0.230	5.31	5.84	
LC	0.100 TP		2.54	I TP	6
LD	0.016	0.021	0.41	0.53	7,11
LL	0.500	0.750	12.70	19.05	7
LU	0.016	0.019	0.41	0.48	12
L1	-	0.050	-	1.27	7
L2	0.250	-	6.35	-	7
Р	0.100	-	2.54	-	5
Q	-	0.040	-	1.02	4
TL	0.028	0.048	0.71	1.22	3
TW	0.036	0.046	0.91	1.17	9
r	-	0.010	-	0.25	10
α	45°	TP	45° TP		6



NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for information only.
- 3. Symbol TL is measured from HD maximum.
- 4. Details of outline in this zone are optional.
- 5. Symbol CD shall not vary more than 0.010 (0.25 mm) in zone P. This zone is controlled for automatic handling.
- 6. Leads at gauge plane 0.054 inch (1.37 mm) +.001 inch (0.03 mm) -0.000 inch (0.00 mm) below seating plane shall be within 0.007 inch (0.18 mm) radius of true position (TP) relative to tab. Device may be measured by direct methods or by gauge.
- 7. Symbol LD applies between L1 and L2. Dimension LD applies between L2 and LL minimum.
- 8. Lead number three is electrically connected to case.
- 9. Beyond r maximum, TW shall be held for a minimum length of 0.011 inch (0.28 mm).
- 10. Symbol r applied to both inside corners of tab.
- 11. Measured in a zone beyond 0.250 (6.35 mm) from the seating plane.
- 12. Measured in the zone between 0.050 (1.27 mm) and 0.250 (6.35 mm) from the seating plane.
- 13. In accordance with ASME Y14.5M, diameters are equivalent to φx symbology.
- 14. Lead 1 is emitter, lead 2 is base, and case is collector.